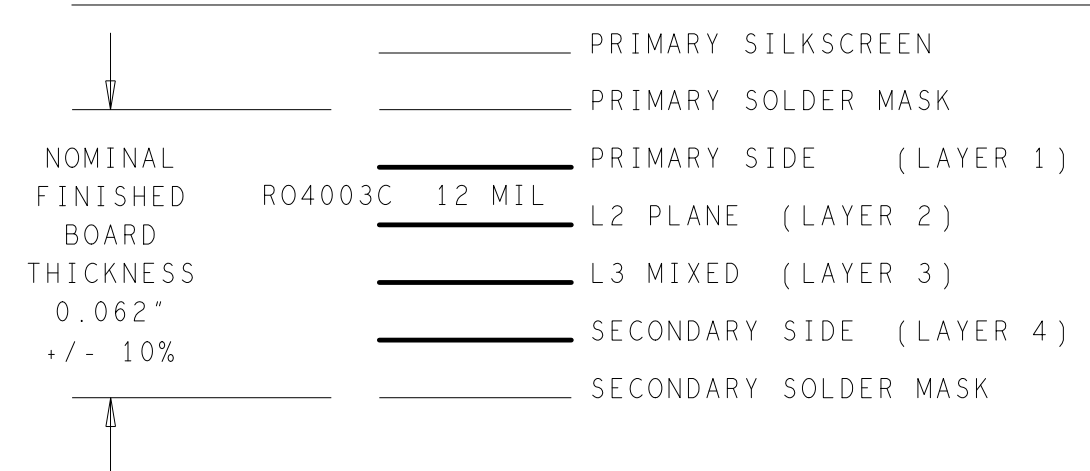


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	14FEB20	M. DOGAN

4 LAYER STACKUP

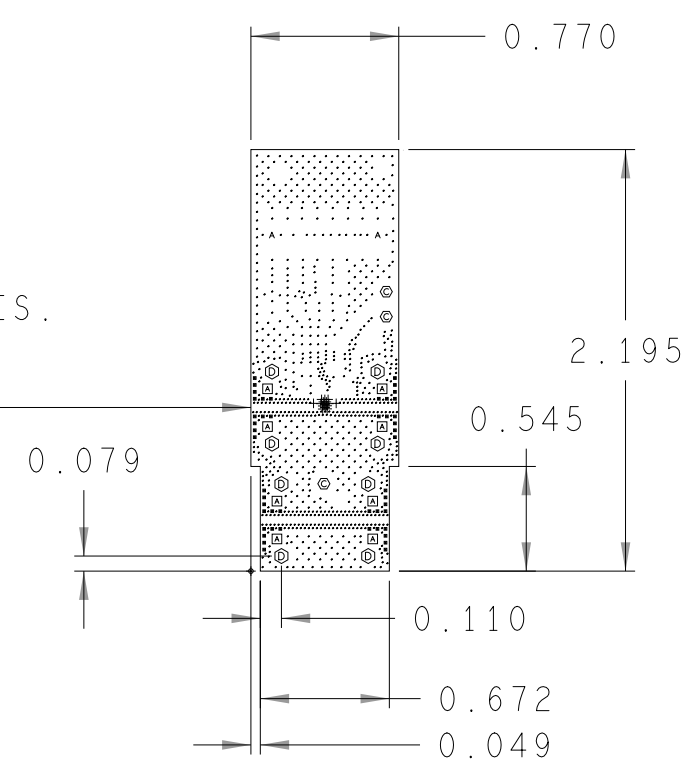


HOLE TOLERANCE

UNLESS SPECIFIED
PLATED: $\pm .003$
NON PLATED: $\pm .003$

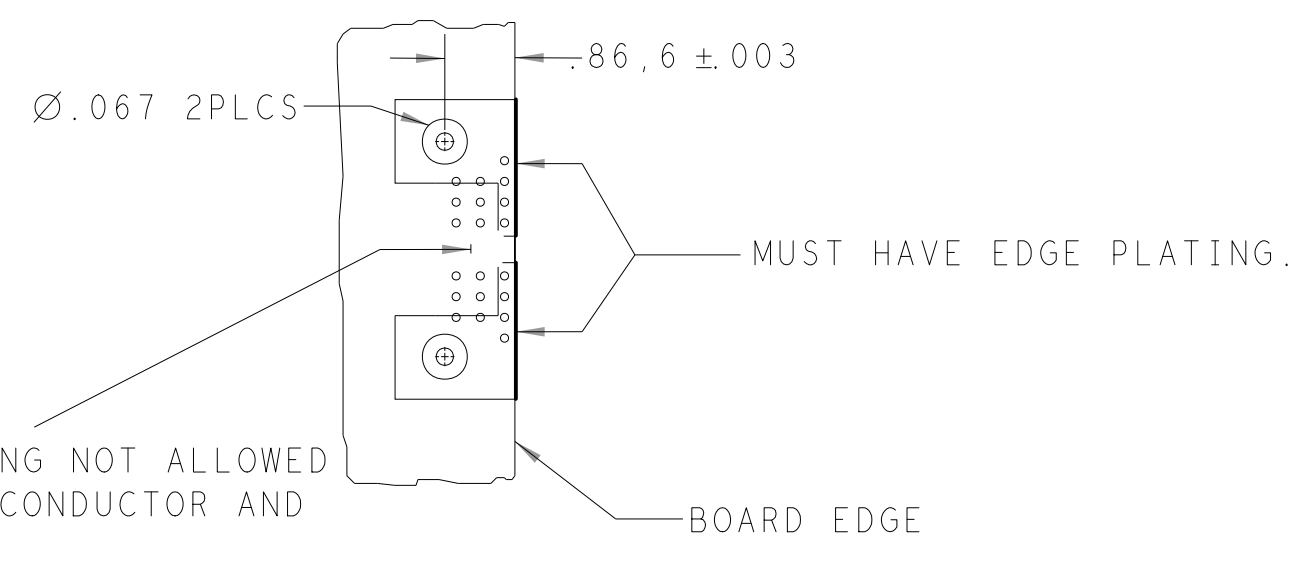
FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	8.0	PLATED	15	SEE NOTE 15
.	10.0	PLATED	856	SEE NOTE 15
-	14.0	PLATED	48	SEE NOTE 15
⊙	63.0	PLATED	3	
⊗	67.0	PLATED	8	
⊖	78.0	PLATED	8	
×	39.0	NON-PLATED	2	

SEE DETAIL A, B & C FOR 4 PLACES.



DETAIL "A"

HV-LR-SR2(12)-DETAIL



4 PLACES

NOTES APPLY TO PATTERN REGARDLESS OF ORIENTATION.

SPECIFICATIONS:

ROHS COMPLIANCE NOTE; HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLIANT
THE EU RoHS DIRECTIVE 2002/95/EC.

MATERIALS; ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM
IPC-4101 OR IPC-4103, MINIMUM $T_g > 170^{\circ}\text{C}$, $T_d > 300^{\circ}\text{C}$,
U.L. RATING OF 94 V-0

MATERIAL FAMILY; RO4003C 12 MIL / ISOLA 370HR

CLADDING: EXTERNAL LAYERS .5 OZ. COPPER, OVERPLATE TO 2.2 MIL.
INTERNAL PLANE LAYERS .5 OZ. COPPER.

NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE
CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL
TAKE PRECEDENCE.

SOLDER MASK; SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES
OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840
(LATEST REV.) CLASS 3. COLOR GREEN.

SILK SCREEN; SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR: WHITE
SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS,
COLOR: WHITE

SURFACE FINISH: ENIG (Electroless Nickel/Immersion Gold)
PER IPC-4552 LATEST REVISION

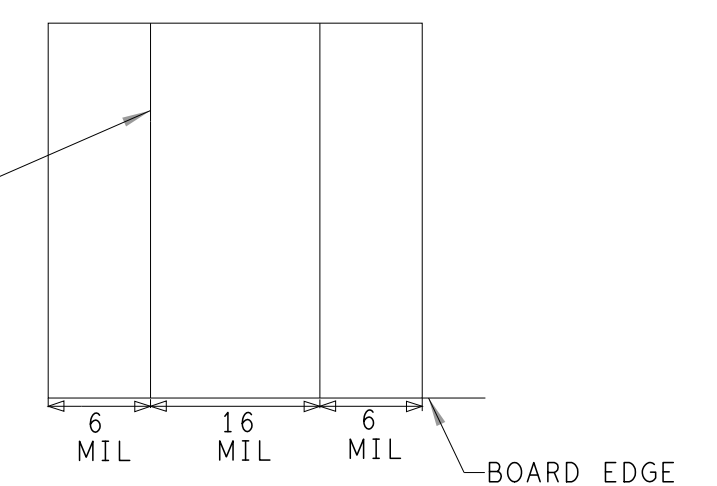
INTENTIONAL SHORTS; IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN
INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL
IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT
DOES NOT MATCH "READ_ME.2" FILE PROVIDED.

TEST REQUIREMENTS; 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

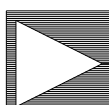
REQUIREMENTS:

1. REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
2. ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115, (LATEST REVISION.)
3. MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
4. HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
5. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
6. HOLE DIAMETERS APPLY AFTER PLATING.
7. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
8. MINIMUM DESIGN LINE WIDTH IS 6 MIL.
9. MINIMUM DESIGN SPACING IS 4.7 MIL.
10. NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.
11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
12. THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
 - A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
 - B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
13. MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
 - ~~A. U.L. CODE FLAMMABILITY RATING~~
 - D. MFR LOGO
 - B. DATE CODE (STAMP).
 - E. SUCCESSFUL ELECTRICAL TEST.
 - C. LOT NUMBER
14. REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED. REPAIRS ARE NOT ALLOWED IN ANY AREA DEFINED ON GOLD_PRM AND/OR GOLD_SEC ARTWORK LAYERS WHEN PROVIDED IN GERBER OR ODB++ DATA.
15. VIAS INDICATED TO BE FILLED WITH NON-CONDUCTIVE EPOXY GROUND FLUSH AND PLATED OVER. COPLANAR ON PRIMARY SIDE DIMPLE WITHIN <1 MIL PRIOR TO FINAL PLATING. PROTRUSIONS (BUMPS) ON FILLED VIAS ARE NOT ALLOWED.
16. CONNECTOR AREAS TO BE EDGE PLATED, PLATING MUST CONNECT ALL FOUR LAYERS. EDGE PLATING MUST BE REMOVED FOR CENTER CONNECTOR AREAS. SEE DETAIL B. BOARD CUTTING SHOULD BE CONTROLLED TO GET THE DESIRED DIMENSIONS SHOWN IN DETAIL C.
17. CRITICAL LINE WIDTH = 16 MIL +/- 0.5 MIL ON PRIMARY SIDE. ADJUST PROCESS TO ACHIEVE WIDTH. SEE DETAIL C. CRITICAL SPACING WIDTH = 6 MIL +/- 0.5 MIL ON PRIMARY SIDE. ADJUST PROCESS TO ACHIEVE WIDTH. SEE DETAIL C. RECORD RF LINE WIDTHS AND SPACINGS SHOWN IN DETAIL B ON A FIRST ARTICLE REPORT. ONE SAMPLE FROM EACH 10 BOARDS AND MARK THEM BY GIVING NUMBERS.

DETAIL C



PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		APPROVAL		DATE		 <div>ANALOG DEVICES</div>		WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
		TEMPLATE ENGINEER							
DECIMALS FRACTIONS ANGLES .XX . . .010 . . 1/32 . . 2 .XXX . . .005 XXXX . . .0050		HARDWARE SERVICES M. JOSE HARDWARE SYSTEMS		14FEB20		<div>TITLE</div> <div>FABRICATION</div> <div>ADRF5740 EVAL Z</div>			
MATERIAL		TEST ENGINEER							
		COMPONENT ENGINEER							
		TEST PROCESS							
		HARDWARE RELEASE							
FINISH		DESIGNER MEHMET DOGAN PTP ENGINEER T. KOLCUOGLU CHECKER M. LAGO		14FEB20 14FEB20 14FEB20		SIZE	FSCM NO	DRAWING NUMBER	REV
						D	24355	09-064381	A
DO NOT SCALE DWG				SCALE 1/1		SHEET 1 OF 1			